

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01457	5.0	0.21
	Lead alloy	Silver (Ag)	7440-22-4	0.00729	2.5	0.105
	Lead alloy	Lead (Pb)	7439-92-1	0.26956	92.5	3.885
			<b>Subtotal</b>	<b>0.29142</b>	<b>100</b>	<b>4.2</b>
Die	Doped silicon	Silicon (Si)	7440-21-3	0.42325	100.0	6.1
			<b>Subtotal</b>	<b>0.42325</b>	<b>100</b>	<b>6.1</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.01333	100.0	0.19218
			<b>Subtotal</b>	<b>0.01333</b>	<b>100</b>	<b>0.19218</b>
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.73463	100.0	25
			<b>Subtotal</b>	<b>1.73463</b>	<b>100</b>	<b>25</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02331	0.04	0.336
	Copper alloy	Iron (Fe)	7439-89-6	0.05828	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	58.20186	99.86	838.824
		<b>Subtotal</b>	<b>58.28345</b>	<b>100</b>	<b>840</b>	
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.39553	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.24466	16.0	90
	Filler	Silica fused	60676-86-0	29.27183	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11709	0.3	1.6875
		<b>Subtotal</b>	<b>39.02911</b>	<b>100</b>	<b>562.5</b>	
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.22481	100.0	3.24
			<b>Subtotal</b>	<b>0.22481</b>	<b>100</b>	<b>3.24</b>
			<b>Total</b>	<b>100</b>	<b>100</b>	<b>1441.23218</b>

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